## CLAIM AMENDMENTS

1. (Currently Amended) An electronic device comprising:

an element-carrying-substrate having an electronic element and a first electrode, the first electrode being disposed on a surface of the element-carrying-substrate and having a first area;

a wiring substrate facing the element-carrying-substrate and having a second electrode disposed on a surface of said wiring substrate, the second electrode having a second area and facing the first electrode; and

a coupler disposed between the first electrode and the second electrode, joining the element-carrying-substrate to the wiring substrate, the coupler-having including a resin body with a surface, and an electrically conductive member, and a occupying from 20% to 80% of the surface comprising a of the resin region body and an electrically conductive region electrically connecting the first electrode to the second electrode.

## Claim 2 (Cancelled).

- 3. (Currently Amended) The electronic device as claimed in claim 1, wherein the electrically conductive member is a joining metal—and the electrically conductive region includes the joining metal that is located on the surface of the coupler.
- 4. (Currently Amended) The electronic device as claimed in claim 1, wherein the electrically conductive member comprises a metal powder with a high melting point and the electroconductive region includes the a joining metal powder that is located on the surface of the coupler film, the metal powder being joined to a the joining metal film.
- 5. (Withdrawn, Currently Amended) The electronic device as claimed in claim 1, wherein the electrically conductive member comprises a metal strip layer joined to a joining metal film, the metal strip layer encircling the resin body as the electrically enductive region.
- 6. (Withdrawn, Currently Amended) The electronic device as claimed in claim 5, wherein the metal strip layer has an opening disposed substantially at a center of the element\_carrying\_substrate and the wiring substrate.

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- 7. (Currently Amended) The electronic device as claimed in claim 1, wherein the resin body-is comprises a thermosetting resin.
- 8. (Currently Amended) The electronic device as claimed in claim 1, wherein the resin body-is comprises a thermoplastic resin.
- 9. (Currently Amended) A coupler with a spherical shape comprising a blend of a joining metal and a resin, wherein the coupler includes body having a surface comprising and an electrically conductive region formed by the member comprising a blend of a joining metal and a resin region formed by occupying from 20% to 80% of the surface of the resin body.
- 10. (Currently Amended) The coupler as claimed in claim <u>4\_9</u>, further comprising <del>a resin body and</del> a metal powder <del>with a high melting point</del>, wherein the metal powder <del>that</del> is located on the surface of the <del>coupler</del> resin body is joined to the joining metal <del>to form</del> the electrically conductive region.

Claims 11 and 12. (Cancelled).

- 13. (Currently Amended) The coupler as claimed in claim 10, wherein the resin body—is comprises a thermosetting resin.
- 14. (Currently Amended) The coupler as claimed in claim 10, wherein the resin body—is comprises a thermoplastic resin.

## AMENDMENTS TO THE DRAWINGS

Six sheets of replacement drawings are attached, including Figures 1-17. The replacement drawings conform sectional areas, where present, to cross-hatching requirements of U.S. practice and eliminate solid black regions.

Attachment: Replacement Sheet(s)